Y H

Item And Code No.

I T E M	CONNECTOR
S P E C	2.00㎜ Pitch Wire to Board DIP Type
M A K E R S P E C	
Code No.	

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Specification Approval Sheet

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Pitch	2.00 mm
Special	Wire to Board
Type	DIP

SM200S Series
Connector 제품규격
Product Specification

Indemnification

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● 제,개정 이력『History Revision』

NO	DATE	ISS.	CHK.	APP.	SUMMARY
1	2012.09.26	L.J.H	K.S.I	C.G.N	Presentation
2	2013.10.01	L.J.H	Y.M.K	C.G.N	웨이퍼 : 부상높이 0.2mm 증대

아래와 같이 사양 승인원을 제출합니다.

『Yeon Ho Electronics CO.,LTD. submits the approval certification of connector specification.』

1. 업 체 명 : (주) 연 호 전 자
   『Manufactured by : Yeon Ho Electronics CO.,LTD.』
2. 기 안 부 서 : 품질관리실
   『Written by : Quality Control Department』

♠♠♠ 목 차 『Contents』 ♠♠♠

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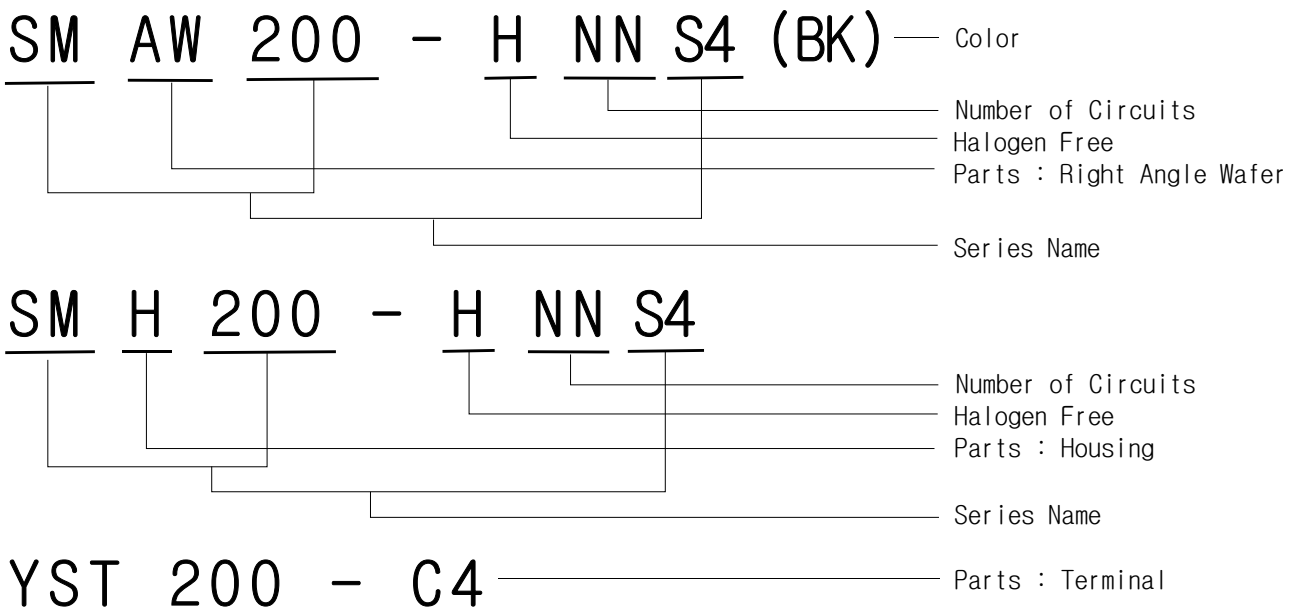
♠♠♠ 별 첨 『Attachment』 ♠♠♠

1. 검사성적서 『Reliability Test Report』
2. 사 양 도 『Drawings』
3. 재질증명서 『Material Certification』
4. 유해물질 분석 Data 『The Analysis Data of Hazardous Substance』
5. 물질안전보건자료 『MSDS Data』
6. Q.C 공정도 『QC Process Chart』

1. 적용 범위 『Scope』

본 사양서는 (주)연호전자 제품 SM200S series DIP type connector에 한하여 적용한다.
『This specification covers the requirements for SM200S series DIP type connector』

2. 형명 구성 『Numbering system of products(Ordering information of products)』



3. 원재료 『Material』

Item	Material	Maker	Over plated / Color
Wafer Material	LCP	Polyplastics	Black
Housing Material	PA66	LG Chem	White
Pin Material	Brass	Poong San	Tin Plated
Hook Material	Brass	Poong San	Tin Plated
Terminal Material	Phosphor Bronze	Poong San	Tin Plated

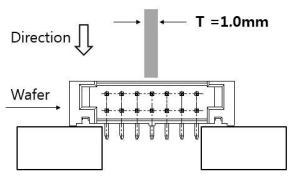
4. 정 격 『Ratings』

항 목 (Item)	정 격 (Standard Data)
정격 전압 (Operating Voltage)	AC/DC 250V
정격 전류 (Current Rating)	AC/DC 3A
사용 온도 (Operating Temperature)	-25℃ ~ +85℃
적용 전선 (Applicable Wire)	AWG #24 ~ #28
적용 PCB (Applicable P.C.B)	1.2 ~ 1.6㎜

5. 성 능 『Performance Characteristics』

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
1.	외 관 치 수 『Dimensions 』		첨부 제품도에 준한다. 『Refer to drawings』
2.	전 기 적 성 능 『Electrical Characteristics』		
	2-1.절연저항	⦿ 인접 Terminal(Contact)간에 DC 500V ±5V 전압을 1분±5초간 인가하였을 때 절연저항을 측정한다. (1회 측정에서 규격 치 미달인 경우 3시간 이내 재측정)	1000MΩ 이상
	2-1.Insulation Resistance	⦿ Measured between adjacent contacts ⦿ Test voltage : DC 500V ±5V / 1 min ±5 sec (Based upon MIL-STD-202G Method 302 Condition B)	1000MΩ MIN
	2-2.내 전 압	⦿ 인접한 Terminal간에 AC 1000V 전압을 1분±5초간 인가한다.	절연파괴/섬락이 없고 사용상 결함이 없을 것
	2-2.Dielectric Withstanding Voltage	⦿ Measured between adjacent contacts ⦿ Test voltage : AC 1000V / 1 min ±5 sec (Based upon MIL-STD-202G Method 301)	No flash over and no physical damage shall be observed
	2-3.접촉저항	⦿ Terminal과 Wafer Pin간의 접촉저항 측정 20mV. 10mA	30mΩ 이하
	2-3.Contact Resistance	⦿ Measured the resistance of mated connector, 20mV. 10mA	30mΩ MAX
3.	물 리 적 성 질 『Physical Characteristics』		
	3-1.납 땜 성	⦿ FLUX (ROSIN 10%, METHANOL 90%)에 5~10초 동안 담근 후 SnAg(3.5)Cu(0.7)의 Pot 납땜조 온도 (240℃±5℃)에 3초±0.5초 동안 침전시킨다.	침전 부위의 납땜이 90% 이상일 것
	3-1. Solder Ability	⦿ Immersion in flux consisting of rosin 10% and methanol 90% for a period of 5 to 10 seconds dip in molten solder consisting of SnAg(3.5)Cu(0.7) at 240℃± 5 ℃degrees for 3 ± 0.5 seconds.	More than 90% of area dipped in molten solder should be coated by solder
	3-2.납땜내열성	※ WAVE TYPE ⦿ 온도 260℃±5℃ 5±0.5초간 침적시킨다.	외관 변형등이 없을 것
	3-2.Solder Heat Resistance	※ WAVE TYPE ⦿ Solder consisting : 260℃±5℃ degrees for 5±0.5 seconds	Appearance : Good

NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
	3-3.Pin유지력	⦿ 사출물(수지)이 Pin을 유지하고 있는 힘 측정 * Pin을 25±3mm/min 속도로 뺄 때의 힘을 측정한다.	0.5Kgf 이상
	3-3.Pin Retention Force	⦿ Measured withdrawal force that resin grips and supports pin * Velocity of withdrawal : 25 ±3mm/min	0.5Kgf MIN
	3-4.총합삽입력	⦿ 회로수가 같은 Housing Ass`Y에 Wafer Ass`Y를 삽입할 때의 힘 측정	POS당 0.3Kgf 이하
	3-4.Total Insertion Force	⦿ Measured forces to insert wafer assembly into the housing assembly which has same circuits	POS X 0.3Kgf MAX
	3-5.총합발거력	⦿ 결합된 Housing Ass`Y로부터 Wafer Ass`Y를 발거할 때의 힘 측정	POS당 0.05Kgf 이상
	3-5.Total Withdrawal Force	⦿ Measured forces to withdraw wafer assembly from the housing assembly which has same circuits	POS X 0.05Kgf MIN
	3-6.내구성시험	⦿ 결합된 제품 Housing Ass`Y과 Wafer Ass`Y의 삽입 및 분리 동작을 10회/분 속도로 30회 행한 후 접촉저항 측정.	접촉저항 : 50mΩ 이하
	3-6.Durability of Contact Resistance	⦿ Measured contact resistance after 30 cycles of total insertion and withdrawal operation. ⦿ Withdrawal Rate : 10th/min.	Contact Resistance : 50mΩ MAX
	3-7.Terminal 삽입력	⦿ Housing을 고정시키고 Terminal를 25 ±3㎜/min 속도로 일직선으로 삽입할 때의 삽입력 측정.	1.0Kgf 이하
	3-7.Insertion Force of Terminal	⦿ Insert a terminal into housing straightly and measure insertion force ⦿ Velocity of insertion : 25 ±3mm/min	1.0Kgf MAX
	3-8.Terminal 조립강도	⦿ Housing에 Terminal을 조립한 후 Terminal을 25 ±3mm/min 속도로 인장시켜 이탈될 때의 힘 측정	0.5Kgf 이상
	3-8.Terminal Retention Force	⦿ Insert a terminal into the housing and measure the force to withdraw the terminal from housing. ⦿ Apply axial pull out force at the speed rate of 25 ±3mm/minute	0.5Kgf MIN
	3-9.압착강도	⦿ Terminal에 Lead Wire를 압착한후 압착부위(심선부위)가 파괴될 때까지 25 ±3㎜/min 속도로 인장강도 측정.	AWG #24 : 2.0Kgf MIN AWG #26 : 1.5Kgf MIN AWG #28 : 1.0Kgf MIN
	3-9.Crimp Tensile Strength	⦿ Measured tensile strength of the crimped contact (stripped wire barrel section of contact) to conductor joint	
	3-10.사출물 파괴강도	⦿ 사출물의 파괴강도를 측정한다. ⦿ 시험 속도 : 25 ±3mm/min	1.0Kgf 이상
	3-10.Insulator Broken Force	⦿ Measured the broken force of the insulator. ⦿ Testing speed : 25 ±3mm/min	1.0Kgf MIN



NO.	시험항목 『Test Title』	시 험 방 법 및 조 건 『Test Procedures/Methods Conditions』	규 격 『Requirements』
4.	환 경 시 험 『Environmental Test』		
	4-1.내진동성 시 험	⊙ DC 100mA 통전상태에서 진폭1.52mm 진동수 10-55-10HZ 진동 상태에서 X,Y,Z방향으로 각각 2시간씩 진동을 시킨 후 단전상태 및 접촉저항 측정	1)접촉저항: 50mΩ 이하 2)단전상태: 1μsec 동안 단전상태 없을것
	4-1.Vibration	⊙ Current of 100mA shall be applied during the testing The vibration shall be along each axis for the period of two hours with the maximum amplitude of 1.52mm and frequency of 10-55-10Hz/Min (Based upon MIL-STD-202G Method 201A)	1)Contact Resistance : 50mΩ MAX 2)Discontinue : 1μsec MAX
	4-2.염수분무 시 험	⊙ Connector를 결합한 상태에서 아래 조건으로 시험 후 흐르는 물에 세척 후 상온에서 4시간 방치 후에 특성을 측정한다. 조건: 염수농도 5% ±1% 염수분무 시간 48시간 ±4시간 시험온도 35℃ ±2℃	1)접촉저항: 50mΩ 이하 2)외관: 흑녹현상 없을것
	4-2.Salt Spray	⊙ Measure after exposure to salt solution spray of 5 ±1% density at a temperature of 35℃ ±2℃ for 48hrs ±4hrs. after test wash and leave to dry (Based upon MIL-STD-202G Method 101E Condition B)	1)Contact Resistance : 50mΩ MAX 2)Appearance : Not black rust
	4-3.내습성시험	⊙ Connector를 결합한 상태에서 아래조건에 따라 시험을 행한 후 측정한다. 조건 : 시험조의 온도 40℃ ±2℃ 상 대 습 도 90% ~ 95% 시 험 시 간 96시간	1)절연저항: 500MΩ 이상 2)접촉저항: 50mΩ 이하 3)외관 : 양호할 것
	4-3.Humidity	⊙ Mated connector shall be left for 96 hours in an environment of 40 ±2℃, and 90 ~ 95% humidity. After the exposure the connector shall be left in an ambient condition for one hour before the measurement is done (Based upon MIL-STD-202G Method 103B Condition B)	1)Insulation Resistance : 500MΩ MIN 2)Contact Resistance : 50mΩ MAX 3)Appearance : Good
	4-4.내고온성 시 험	⊙ Connector를 결합한 상태에서 시험조의 온도 85 ±2℃에서 96시간 동안 시험 후 상온에서 30분간 방치 후 측정한다.	1)접촉저항: 50mΩ 이하
	4-4.Resistance to High Temperature	⊙ Chamber temperature : 85 ±2℃ Exposed 30 minutes after being exposed 96 hours under the chamber temperature electrical characteristics were measured and tested (Based upon MIL-STD-202G Method 108A Condition A)	1)Contact Resistance : 50mΩ MAX
	4-5.내한성시험	⊙ Connector를 결합한 상태에서 시험조의 온도 -40 ±3℃에서 96시간 동안 시험 후 상온에서 30분간 방치 후 측정한다.	1)접촉저항: 50mΩ 이하
	4-5.Altitude Low Temperature	⊙ Chamber temperature : -40 ±3℃ Exposed 30 minutes after being exposed 96 hours under the chamber temperature electrical characteristics were measured and tested (Based upon JIS C60068-2-1)	1)Contact Resistance : 50mΩ MAX

<table>
<tr><th>NO.</th><th>시험항목
『Test Title』</th><th>시 험 방 법 및 조 건
『Test Procedures/Methods Conditions』</th><th>규 격
『Requirements』</th></tr>
<tr><td></td><td>4-6.열충격시험</td><td>⊙ Connector를 결합한 상태에서 아래조건에 따라 5회 연속 시험을 행한 후 시험을 실시한다.
<table>
<tr><td>단 계</td><td>1</td><td>2</td><td>3</td><td>4</td></tr>
<tr><td>온도(℃)</td><td>-55 +0 -3</td><td>25 +10 -5</td><td>85 +3 -0</td><td>25 +10 -5</td></tr>
<tr><td>시간(분)</td><td>30</td><td>5</td><td>30</td><td>5</td></tr>
</table></td><td>1)내전압: 절연파괴 및 섬락이 없고 사용상 결함이 없을 것
2)접촉저항: 50mΩ 이하
3)절연저항: 500MΩ 이상
4)외관 : 양호할 것</td></tr>
<tr><td></td><td>4-6.Thermal Shock</td><td>⊙ Mated connector shall be exposed five cycles as table #1 (Based upon MIL-STD-202G Method 107-A table #1)
<table>
<tr><td>STEP</td><td>1</td><td>2</td><td>3</td><td>4</td></tr>
<tr><td>Temperature (℃)</td><td>-55 +0 -3</td><td>25 +10 -5</td><td>85 +3 -0</td><td>25 +10 -5</td></tr>
<tr><td>Exposed Time (MIN)</td><td>30</td><td>5</td><td>30</td><td>5</td></tr>
</table></td><td>1)Dielectric Strength : No flash over and no physical damage shall be observed
2)Contact Resistance : 50mΩ MAX
3)Insulation Resistance : 500MΩ MIN
4)Appearance : Good</td></tr>
</table>

6. 포장 및 식별방법 『Identification and Packing』

1) 포장 조건 『Packing condition』 : Emboss Taping

2) 포장 방법 『Packing Method』 :

Connector를 Embossed Tape에 포장 후 물리적 변형 또는 화학적 변화가 일어나지 않도록 Reel에 감아야하며 규격 및 수량표시를 한다.

『 2-1. Connector should be into the embossed tape.
The tape shall be sealed with cover tape by heat treatment
2-2. After sealed the embossed tape shall be wound to reel.
2-3. The wound reel shall be packaged in a carton box for shipment must have enough strengths in other to protect physical damage during transportation.』

3) 식별 표시 : 다음과 같은 사항을 제품포장 BOX에 명기한다.

『Identifications shall be marked as follows』

3-1. 제조회사, 제조자명 또는 상표 『Manufacture's LOGO』

3-2. 형명 또는 부품번호 『Part Number』

3-3. 수 량 『Quantity』

3-4. 제조 LOT NO 『Date Code』

3-5. 기타 상호 필요하다고 인정되는 사항
『Others agreed with manufacturer and customer』

7. 사용상 주의사항 『Caution for Use』

본 connector는 강(强)Lock 사양이므로, Connector 감합후의 Wire Harness의 부정확한 취급방향이나 과도하게 잡아당길 경우에는 납땜부의 파괴, Lock등 Connector자체의 파괴 또는 실장기판의 파괴등 Trouble를 발생시킬 가능성이 있습니다.
이와 같은 Trouble을 미연에 방지하고, Connector 성능을 충분히 내기 위해서는, Wire Harness를 취급할 때 다음과 같은 주의를 바랍니다.

『This connector is secure lock type, so the connector must be treated with care after mated. Incorrect handling direction and excessive pulling load to the wire harness may cause troubles which affect its performances such as degradation at solder tail, breakage of connector itself (lock devise, etc.) and a PCB for mounting. To prevent these troubles and make full use of connector's performances, special care should be taken on the following points when handling the wire harness.』

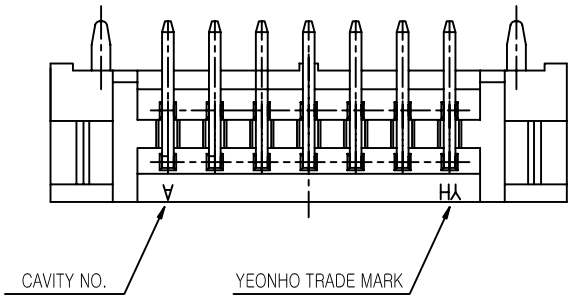
1) Connector에는 평소 Wire Harness 취급할 때, 인장하중 이외에 외력을 지속적으로 가하지 않는다.
『Do not apply an external force to a connector continuously except for pulling load and so on when handling wire harness as usual.』

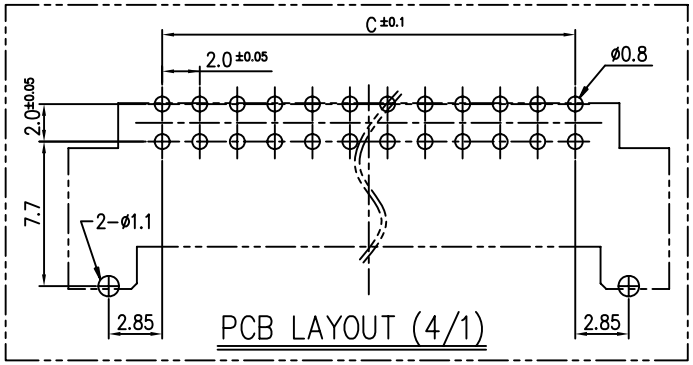
2) 전선에는 Connector의 삽발작업이 무리없이 이루어 질 수 있도록 “느슨하게” 설계하고 삽발작업은 감합축 선으로 한다.
『For the wire, make an appropriate looseness to mate and unmate the connector on the mating axis without strain.』

3) Connector에서 Wire Harness를 분리할 때에는 Lock을 완전히 해제하고 발거한다.
『When withdraw wire harness from the connector, Lock should be unlocked perfectly and withdraw.』

출도일	/ /	연구소

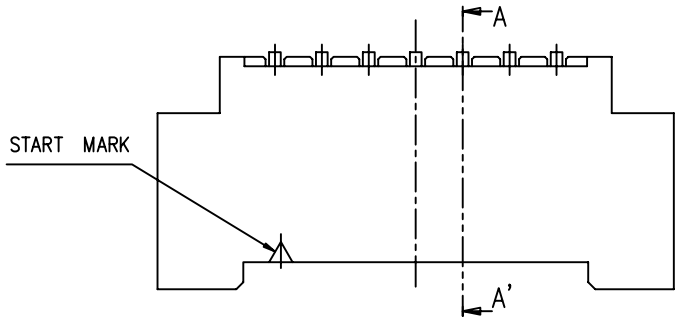
NO. OF POS.	PARTS NO.	A	B	C	D
10	SMAW200-H10S4	18.0	10.7	8.0	14.7
12	SMAW200-H12S4	20.0	12.7	10.0	16.7
14	SMAW200-H14S4	22.0	14.7	12.0	18.7
16	SMAW200-H16S4	24.0	16.7	14.0	20.7
18	SMAW200-H18S4	26.0	18.7	16.0	22.7
20	SMAW200-H20S4	28.0	20.7	18.0	24.7
22	SMAW200-H22S4	30.0	22.7	20.0	26.7
24	SMAW200-H24S4	32.0	24.7	22.0	28.7
26	SMAW200-H26S4	34.0	26.7	24.0	30.7
28	SMAW200-H28S4	36.0	28.7	26.0	32.7
34	SMAW200-H34S4	42.0	34.8	32.0	38.7

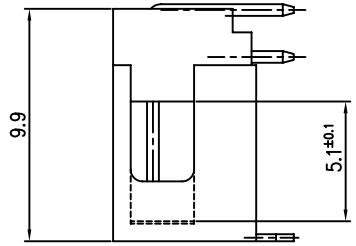


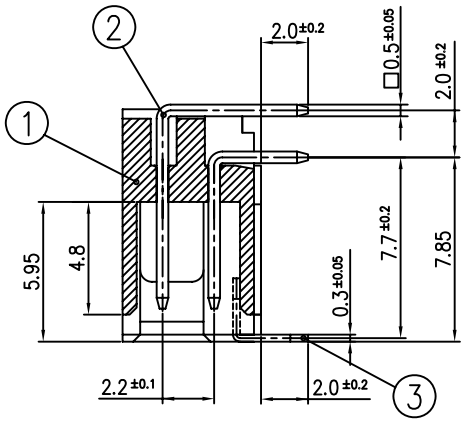


PCB LAYOUT (4/1)

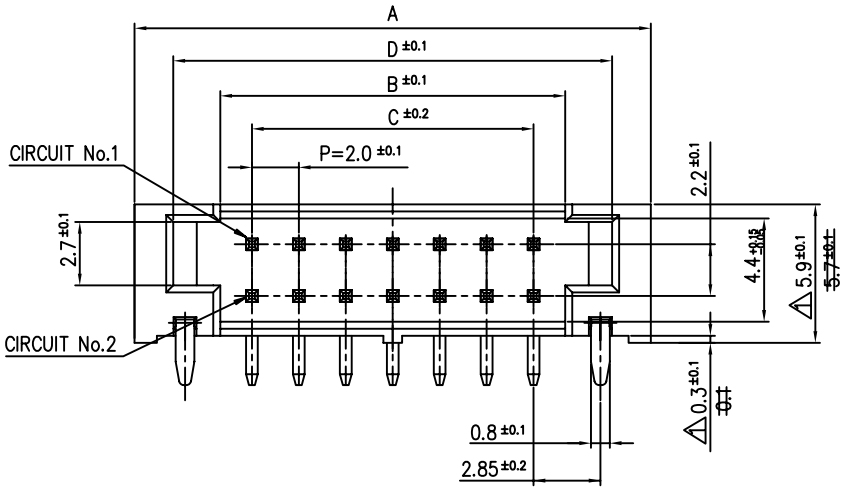
주:
1. GENERAL TOLERANCE ±0.3
2. 관련부품: HOUSING : SMH200-HNNS4
TERMINAL: YST200-C4
WAFER : SMAW200-HNNS4
HOOK : SMAW200-LR2
3. PART NO. SMAW200-HNNS4







SECTION A-A'



3	HOOK	BRASS	2	TIN-PLATED
2	PIN	BRASS	NN	TIN-PLATED
1	WAFER	LCP	1	
I/NO	DESCRIPTION	MATERIAL	QTY	REMARK

⚠	부상 높이 0.2mm 증대	13.10.01	NSH	JJH
LTR	REVISION RECORD	DATE	DR	CHK

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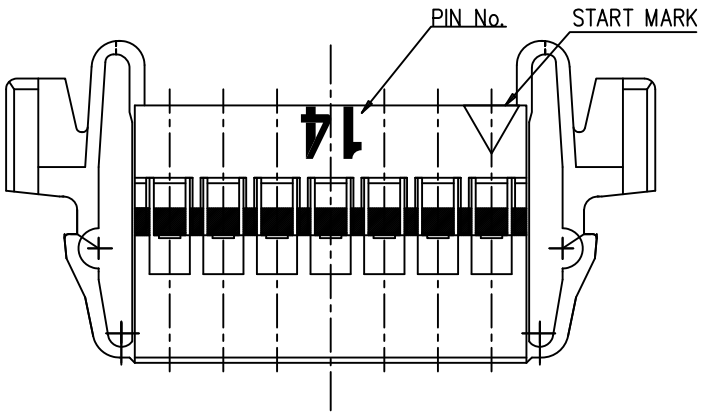
YEONHO ELECTRONICS CO., LTD.

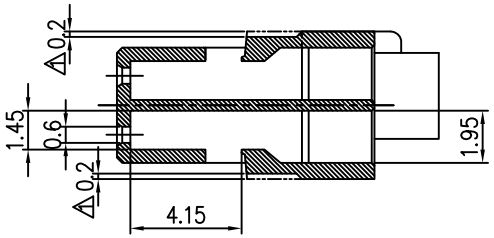
TITLE: SMAW200-HNNS4

SCALE	DRAWN	DESIGN	CHECK	APPD	SIZE		REV
5/1	12.08.16 K.K.S		12.08.16 J.J.H	12.08.16 C.S.W	A3	SMAW200-H00S4-S	01

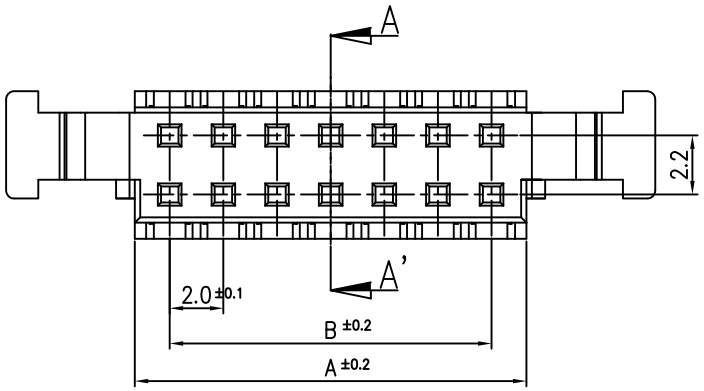
출 도 일	/ / /	연구소

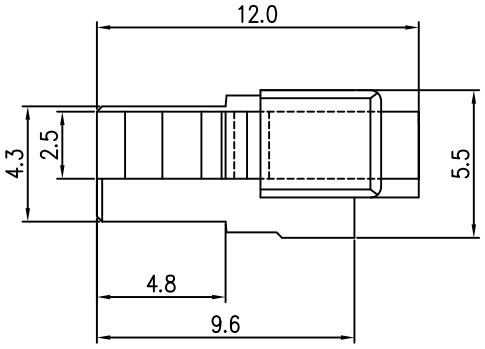
NO. OF POS.	PARTS NO.	A	B	C
12	SMH200-H12S4	12.6	10.0	17.8
14	SMH200-H14S4	14.6	12.0	19.8
16	SMH200-H16S4	16.6	14.0	21.8
18	SMH200-H18S4	18.6	16.0	23.8
20	SMH200-H20S4	20.6	18.0	25.8
22	SMH200-H22S4	22.6	20.0	27.8
24	SMH200-H24S4	24.6	22.0	29.8
26	SMH200-H26S4	26.6	24.0	31.8
28	SMH200-H28S4	28.6	26.0	33.8

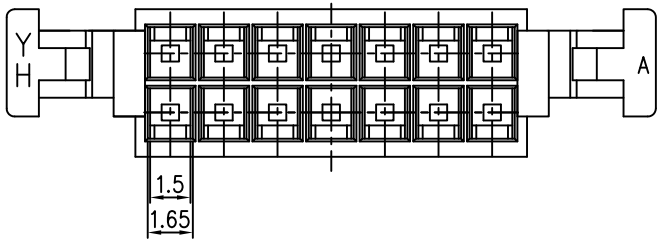


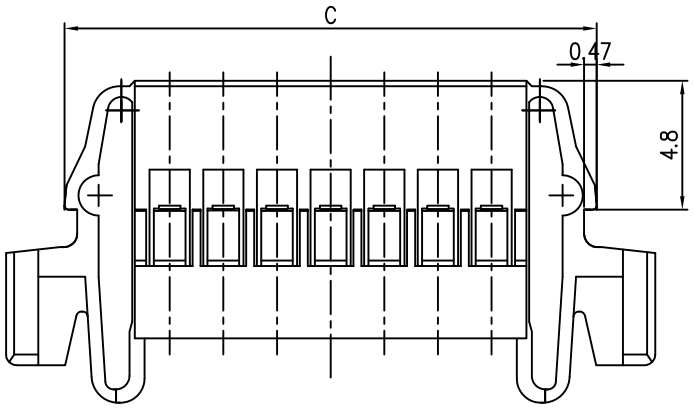


SEC A-A'









주:
1. GENERAL TOLERANCE ±0.3
2. 관련부품: HOUSING : SMH200-HNNS4
TERMINAL : YST200-C4
WAFER : SMAW200-HNNS4
3. PART NO. SMH200-HNNS4

4. WIRE RANGE
- AWG #24 ~ AWG #28.
5. INSULATION DIA : ϕ1.45~ϕ1.2
⚠ϕ1.15~ϕ0.9

1	HOUSING	PA66	1	
I/NO	DESCRIPTION	MATERIAL	QTY	REMARK

⚠	표시부 시방변경(UL10368 전선사용 삽입성 개선)	13.01.22	J.J.H	C.S.W
LTR	REVISION RECORD	DATE	DR	CHK

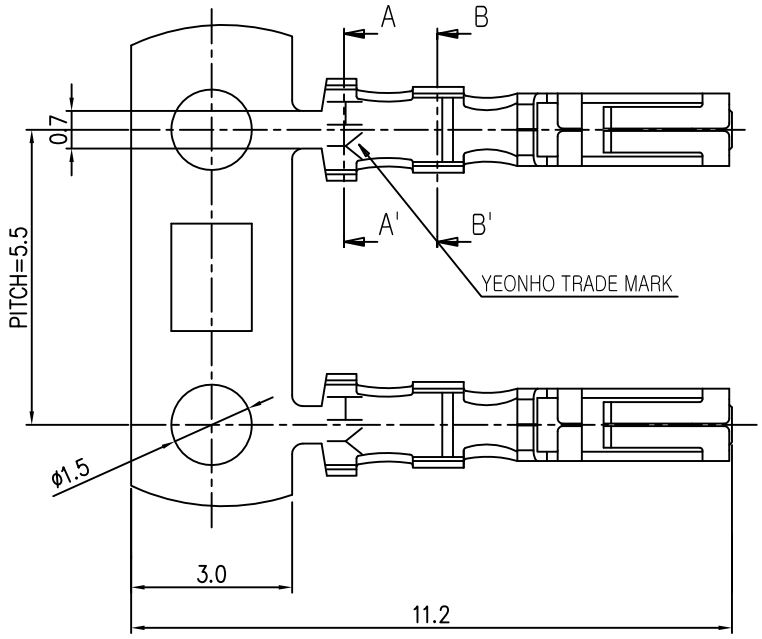
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YEONHO ELECTRONICS CO., LTD.

TITLE: SMH200-HNNS4

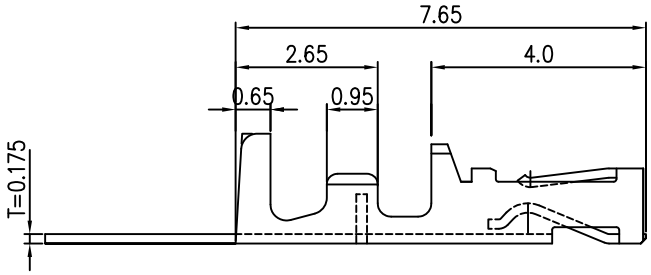
SCALE	DRAWN	DESIGN	CHECK	APPD	SIZE		REV
5/1	12.08.16 K.K.S		12.08.16 J.J.H	12.08.16 C.S.W	A2	SMH200-H00S4-S	1

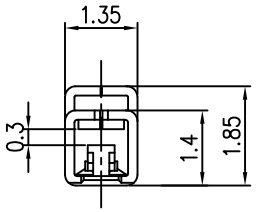
출도일	/ /	연구소

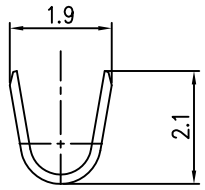


NOTE
1. GENERAL TOLERANCE ±0.3
2. MATING PARTS.
   - HOUSING : SMH200-HNNS4

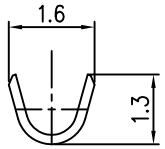
3. WIRE RANGE
   - AWG #24 ~ AWG #28.
4. INSULATION DIA : ϕ1.45~ϕ1.2







SECTION A-A'



SECTION B-B'

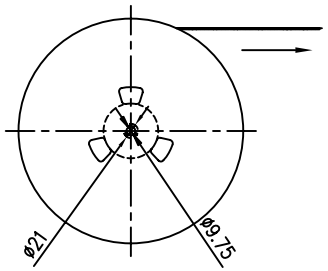
1	TERMINAL	PHOSPHOR BRONZE		TIN_PLATED
I/NO	DESCRIPTION	MATERIAL	QTY	REMARK

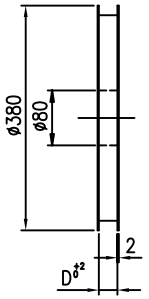
YEONHO ELECTRONICS CO., LTD.					TITLE: YST200-C4	
SCALE	DRAWN	DESIGN	CHECK	APPD	SIZE	REV
10/1	12.08.16 K.K.S		12.08.16 J.J.H	12.08.16 C.S.W	A3 YST200-C4-S	

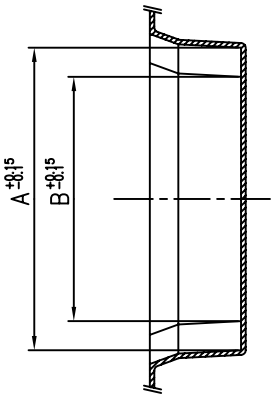
LTR	REVISION RECORD	DATE	DR	CHK

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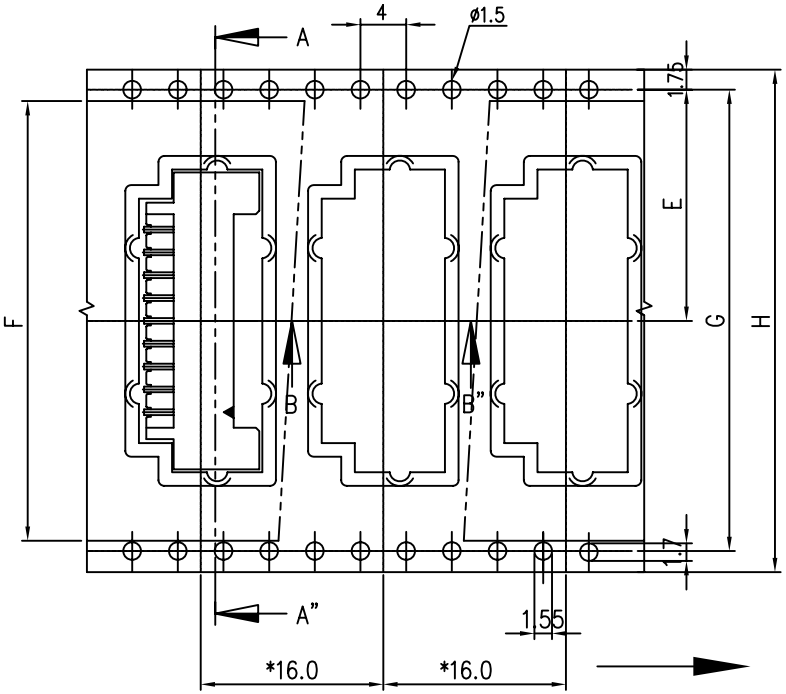
NO. OF POS.	A	B	C	D	E	F	G	H	REMARKS
10	18.5	13.4		33	14.2	26.5	28.4	32.0	
12	20.5	15.4		33	14.2	26.5	28.4	32.0	
14	22.5	17.4		45	20.2	38.5	40.4	44.0	
16	24.5	19.4		45	20.2	38.5	40.4	44.0	
18	26.5	21.4		45	20.2	38.5	40.4	44.0	
20	28.5	23.4		45	20.2	38.5	40.4	44.0	
22	30.5	25.4		45	20.2	38.5	40.4	44.0	
24	32.5	27.4		45	20.2	38.5	40.4	44.0	
26	34.5	29.4		57	26.2	50.5	52.4	56.0	
28	36.5	31.4		57	26.2	50.5	52.4	56.0	
30	38.5	33.4		57	26.2	50.5	52.4	56.0	
34	42.5	37.4		57	26.2	50.5	52.4	56.0	

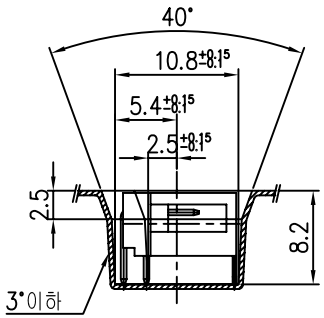






SECTION A–A"(S=2/1)



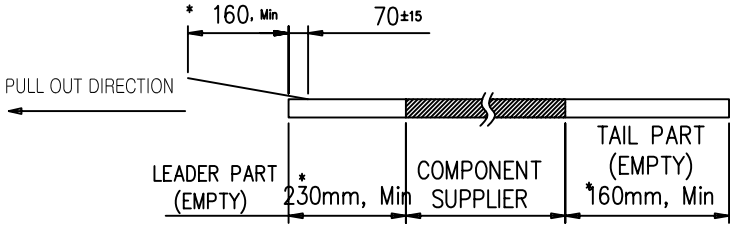


SECTION B–B"(S=2/1)

NOTES

1. NUMBER OF CONNECTOR: 700PCS/REEL

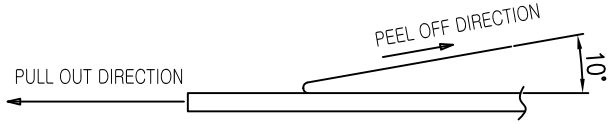
2. LEAD TAPE LENGTH(mm)



"*"표시는 CHIP MOUNT실과 별도 협의 한다.

3. TOP TAPE의 접착강도: 10 ~ 130gf(시험방법: 아래참조)

PEELING SPEED: 300mm/Min



4. 재료: CARRIER TAPE: PS OR PET

COVER TAPE: PET, PE, PEF

REEL: PS

5. 일반공차: ±0.2

	CARRIER TAPE				
I/NO	DESCRIPTION	MATERIAL	TREATMENT	QTY	REMARK

YEONHO ELECTRONICS CO., LTD.

TITLE: SMAW200-NNSH EMBOSS TAPING

SCALE	DRAWN	DESIGN	CHECK	APPD
2/1	10.06.16 K.K.S		10.06.16 J.J.H	10.06.16 Y.Y.W

SIZE	DWG. NO	REV
A3	SMAW200-00SH-P	

LTR	REVISION RECORD	DATE	DR	CHK